

# LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1990is8-10#trpbf

(Engineering Calculation)

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**TOTAL MASS (g) : 0.073417**

| COMPONENT MATERIAL  | VENDOR/ INDUSTRY NAMES           | CONSTITUENT NAME          | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. |
|---------------------|----------------------------------|---------------------------|------------|----------------------|-------------------------------|---------------------------------|
| Active Device       | Linear Technology                | Silicon (Si)              | 7440-21-3  | 0.002001             | 1000000                       | 27255.3242188                   |
| Die Coat            | Dow Corning                      | Silicone                  | 69430-27-9 | 0.000000             | 0                             | 0                               |
| Lead Frame          | A42                              | Copper (Cu)               | 7440-50-8  | 0.000000             | 0                             | 0                               |
|                     |                                  | Iron (Fe)                 | 7439-89-6  | 0.014071             | 580000                        | 191658.984375                   |
|                     |                                  | Phosphorus (P)            | 7723-14-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Zinc (Zn)                 | 7440-66-6  | 0.000000             | 0                             | 0                               |
|                     |                                  | Nickel (Ni)               | 7440-02-0  | 0.010189             | 420000                        | 138782.84375                    |
|                     |                                  | Silicon (Si)              | 7440-21-3  | 0.000000             | 0                             | 0                               |
|                     |                                  | Magnesium (Mg)            | 7439-95-4  | 0.000000             | 0                             | 0                               |
|                     |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                     |                                  | Lead Frame Total:         |            | 0.024260             | 1000000                       | 330441.84375                    |
| Plating             | PMI                              | Exter. Plating Pb         | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                     |                                  | Exter. Plating Sn         | 7440-31-5  | 0.001477             | 1000000                       | 20115.9804688                   |
|                     |                                  | External Plating Total:   |            | 0.001477             | 1000000                       | 20115.9804688                   |
|                     |                                  | Inter. Plating Ni         | 7440-02-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Inter. Plating Ag         | 7440-22-4  | 0.000194             | 1000000                       | 2642.44506836                   |
|                     |                                  | Internal Plating Total:   |            | 0.000194             | 1000000                       | 2642.44506836                   |
| Die Attach          | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag)               | 7440-22-4  | 0.000689             | 750000                        | 9384.76660156                   |
|                     |                                  | Tin (Sn)                  | 7440-31-5  | 0.000000             | 0                             | 0                               |
|                     |                                  | Lead (Pb)                 | 7439-92-1  | 0.000000             | 0                             | 0                               |
|                     |                                  | Silica (SiO2)             | 60676-86-0 | 0.000000             | 0                             | 0                               |
|                     |                                  | Indium (In)               | 7440-74-6  | 0.000000             | 0                             | 0                               |
|                     |                                  | Metal Oxide               |            | 0.000000             | 0                             | 0                               |
|                     |                                  | Antimony (Sb)             | 7440-36-0  | 0.000000             | 0                             | 0                               |
|                     |                                  | Resin (EP)                |            | 0.000230             | 250000                        | 3132.79589844                   |
|                     |                                  | Die Attach Total:         |            | 0.000919             | 1000000                       | 12517.5625                      |
| Encapsulation       | MULTI-AROMATIC RESIN Br/Sb FREE  | Resin (EP)                |            | 0.006657             | 150000                        | 90674.0078125                   |
|                     |                                  | Bromine (Br)              | 40039-93-8 | 0.000000             | 0                             | 0                               |
|                     |                                  | Silica (SiO2)             | 60676-86-0 | 0.036392             | 820000                        | 495690.03125                    |
|                     |                                  | Antimony Trioxide (Sb2O3) | 1309-64-4  | 0.000000             | 0                             | 0                               |
|                     |                                  | Metal Hydroxide           |            | 0.001110             | 25000                         | 15119.1435547                   |
|                     |                                  | Carbon Black (C)          | 1333-86-4  | 0.000222             | 5000                          | 3023.82910156                   |
|                     |                                  | Encapsulation Total:      |            | 0.044381             | 1000000                       | 604507                          |
| Bond Wire Estimated | AFW/TANAKA/ Kn                   | Gold (Au)                 | 7440-57-5  | 0.000185             | 1000000                       | 2519.85742188                   |
|                     |                                  |                           |            |                      | <b>TOTAL MASS (g) :</b>       | <b>0.073417</b>                 |